




















**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
08	146	FR4	35	L20.18_05.35	P10	S1

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**08\_146\_FR4\_35\_L20.18\_05.35\_p10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	35 $\mu$	Copper		} <b>A1</b>	
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)
	100 $\mu$	Prepreg			
<b>Layer-2</b>	18 $\mu$	Copper			} <b>A2</b>
	200 $\mu$	L-FR4			
<b>Layer-3</b>	18 $\mu$	Copper			} <b>A3</b>
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-4</b>	35 $\mu$	Copper			} <b>A2</b>
	50 $\mu$	L-FR4			
<b>Layer-5</b>	35 $\mu$	Copper		} <b>A3</b>	
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-6</b>	18 $\mu$	Copper		} <b>A3</b>	
	200 $\mu$	L-FR4			
	100 $\mu$	Prepreg			
<b>Layer-7</b>	18 $\mu$	Copper		} <b>A2</b>	
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg		} <b>A3</b>	
<b>Layer-99</b>	35 $\mu$	Copper			

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